

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6108xxxC/DGR-G
Typical Mass: 3 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.197	Silicon	65600	7440-21-3
	-	Arsenic	4	7440-38-2
Lead pad	0.558	Nickel	185900	7440-02-0
	0.045	Silver	14900	7440-22-4
	0.008	Gold	2700	7440-57-5
Die attach	0.013	Epoxy Resin	4500	—
	0.010	Silica	3400	60676-86-0
Bonding wire	0.047	Gold	15800	7440-57-5
Resin	1.876	Silica	625400	60676-86-0
	0.043	Silica (crystal)	14300	14808-60-7
	0.106	Epoxy Resin	35500	—
	0.064	Phenol Resin	21200	—
	0.032	Metal Hydroxide	10800	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."